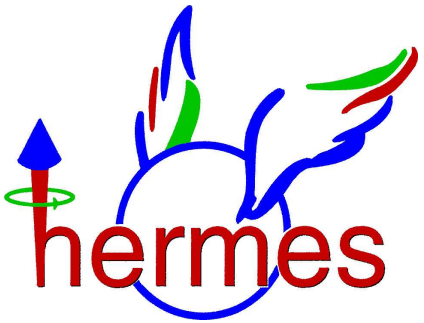
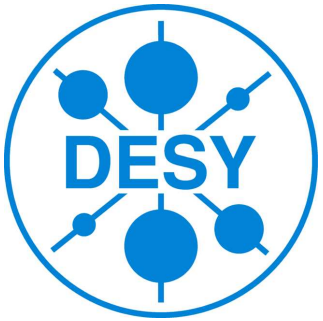
Der Silicon-Detektor bei HERMES,

ein Überblick über Experiment und Ergebnisse
- allgemeinverständlich, nicht nur für Fachleute! -

A. Vandenbroucke, University Gent





S. Balashov, I.-M. Gregor, I. Hristova, M. Kopytin, W. Lange,
J. Stewart, DESY Zeuthen

Outline

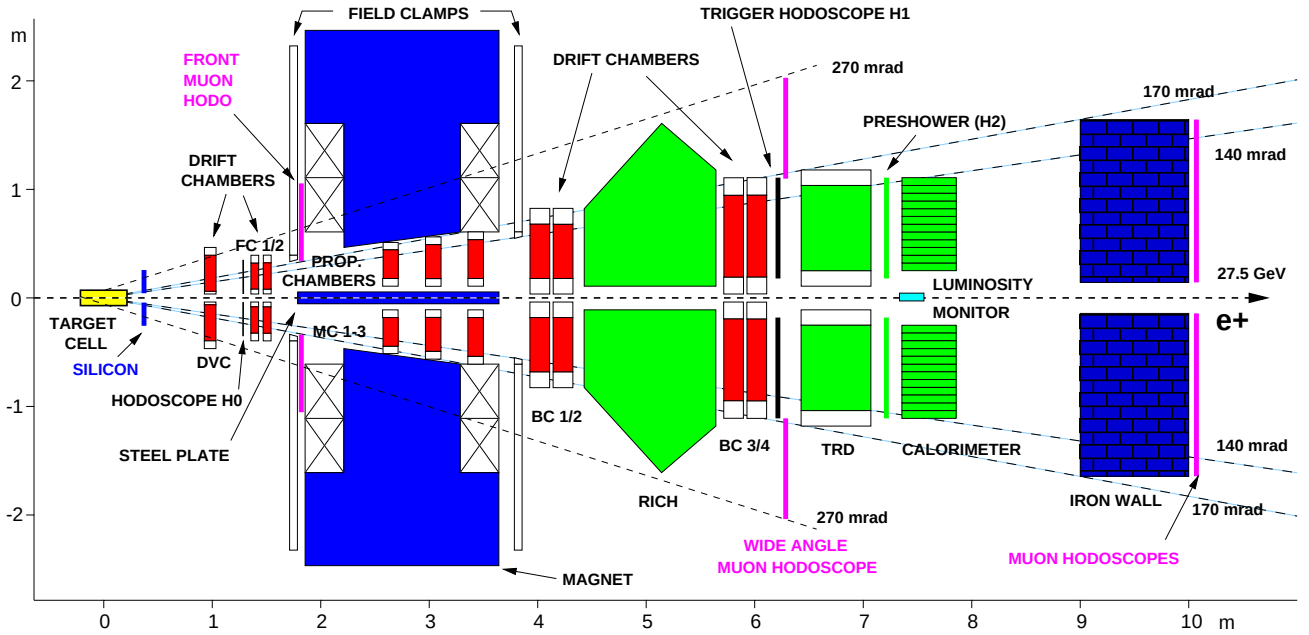
1. The HERMES Experiment
2. Recoil Detector
3. Silicon Recoil Detector
   - ➡ Sensors, Frame, Hybrid, Foils, Tests
4. Summary

The HERMES Experiment

➜ HERA
ME asurement
of Spin

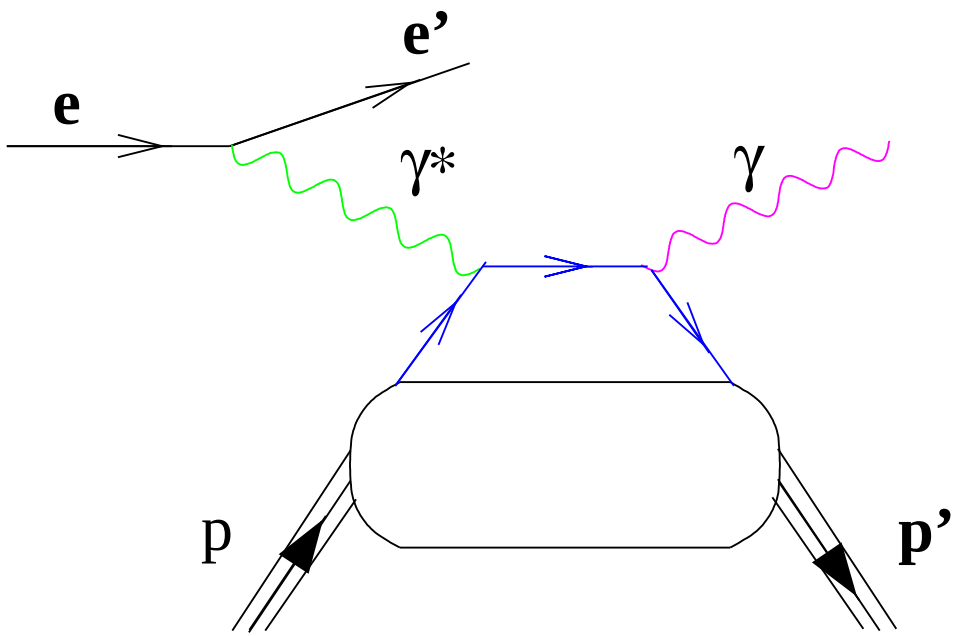
- ➜ Experiment at DESY Hamburg
- ➜ 27,5 GeV longitudinally polarised $e^{\pm}$ from HERA accelerator
- ➜ Spin like Charge fundamental property

The HERMES Experiment



- Internal polarized gas target (H,D ,He,Ne,Kr)
- Tracking: Silicon, Drift Chambers
- PID: RICH, TRD, E/p Calorimeter

The HERMES Experiment

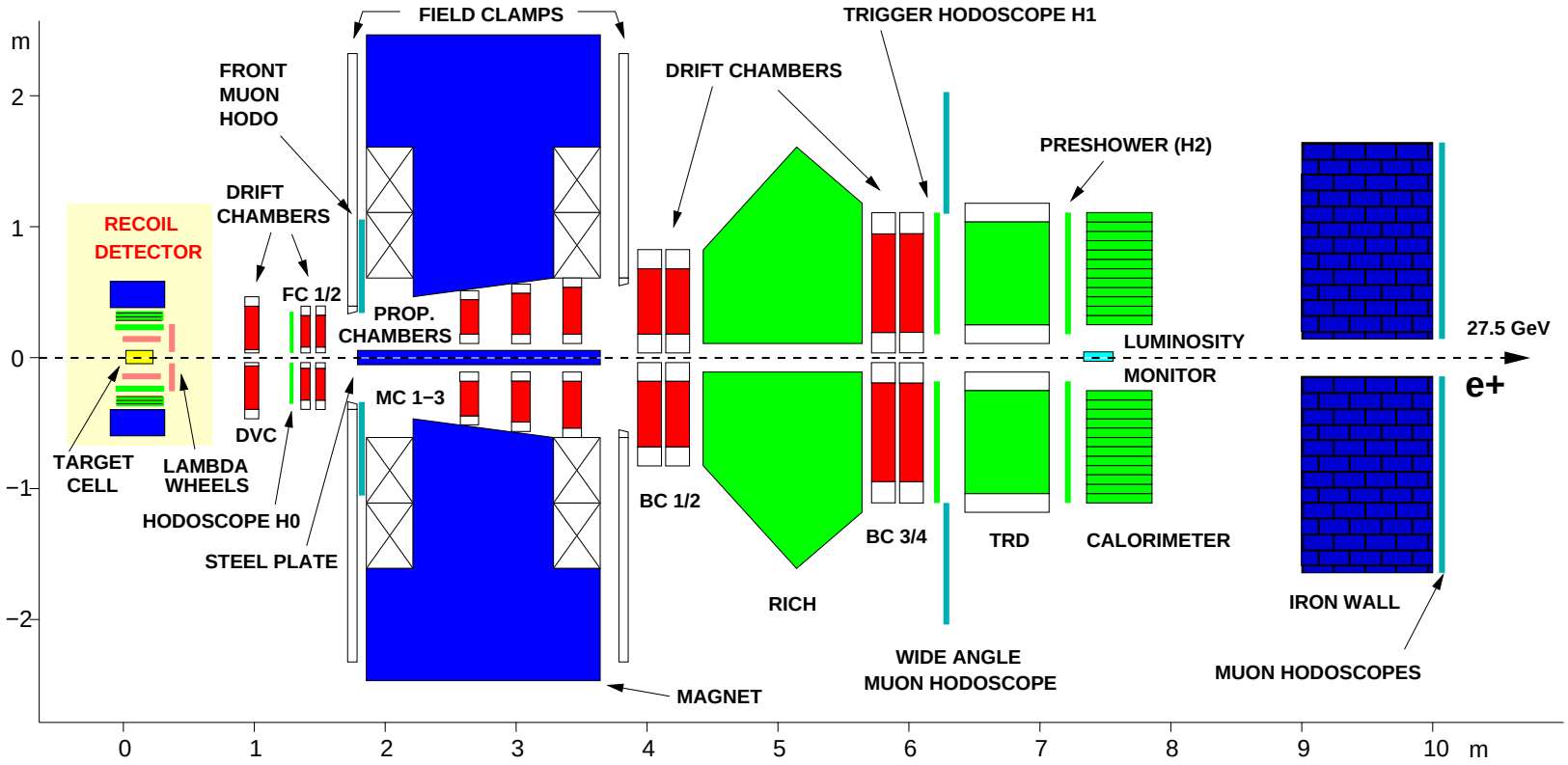


Exclusive Processes:

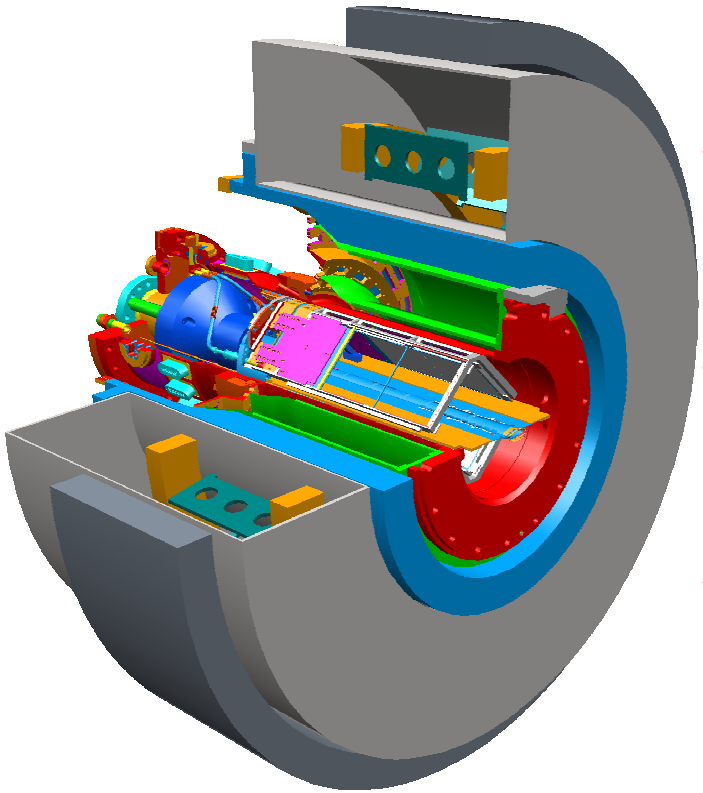
initial and final state fully known !

A Recoil Detector for HERMES

To improve the measurement of exclusive processes a **Recoil Detector** is presently being built.

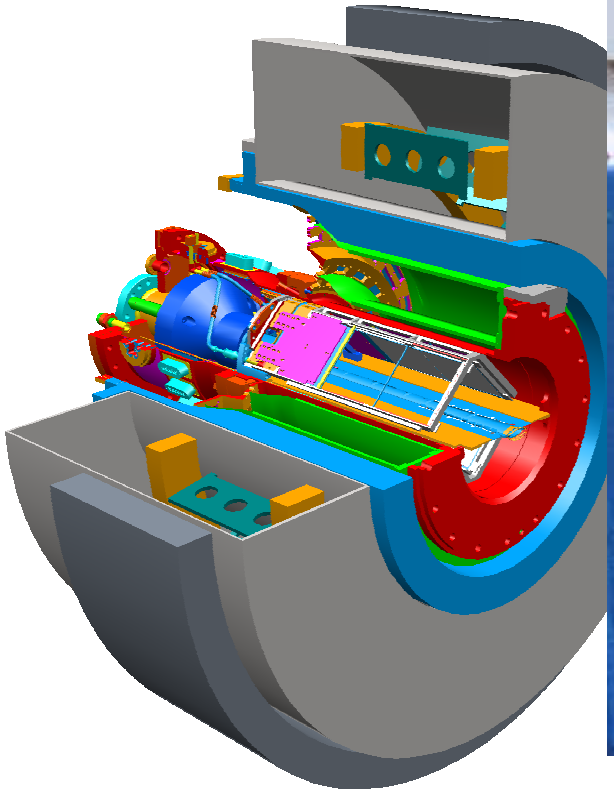


A Recoil Detector for HERMES



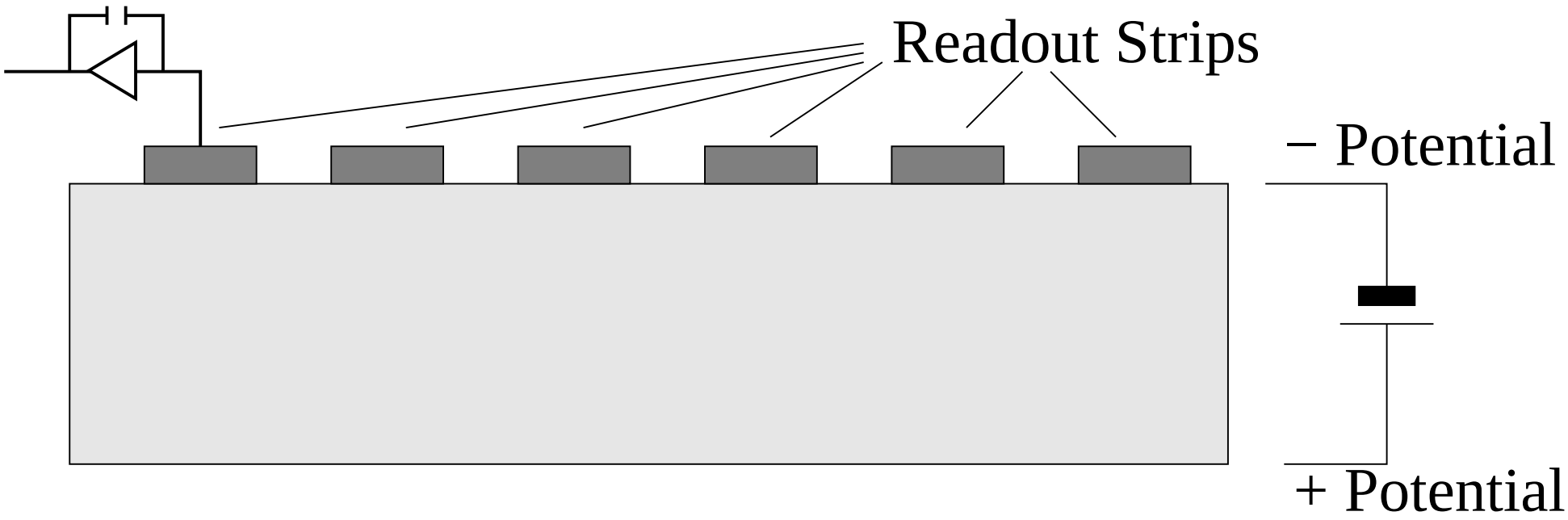
- Silicon measuring low momenta protons
- SciFi for momentum and tracking
- Photon detector to improve exclusivity
- Superconducting Magnet providing field for SciFi
- A new collimator to reduce background hits

A Recoil Detector for HERMES

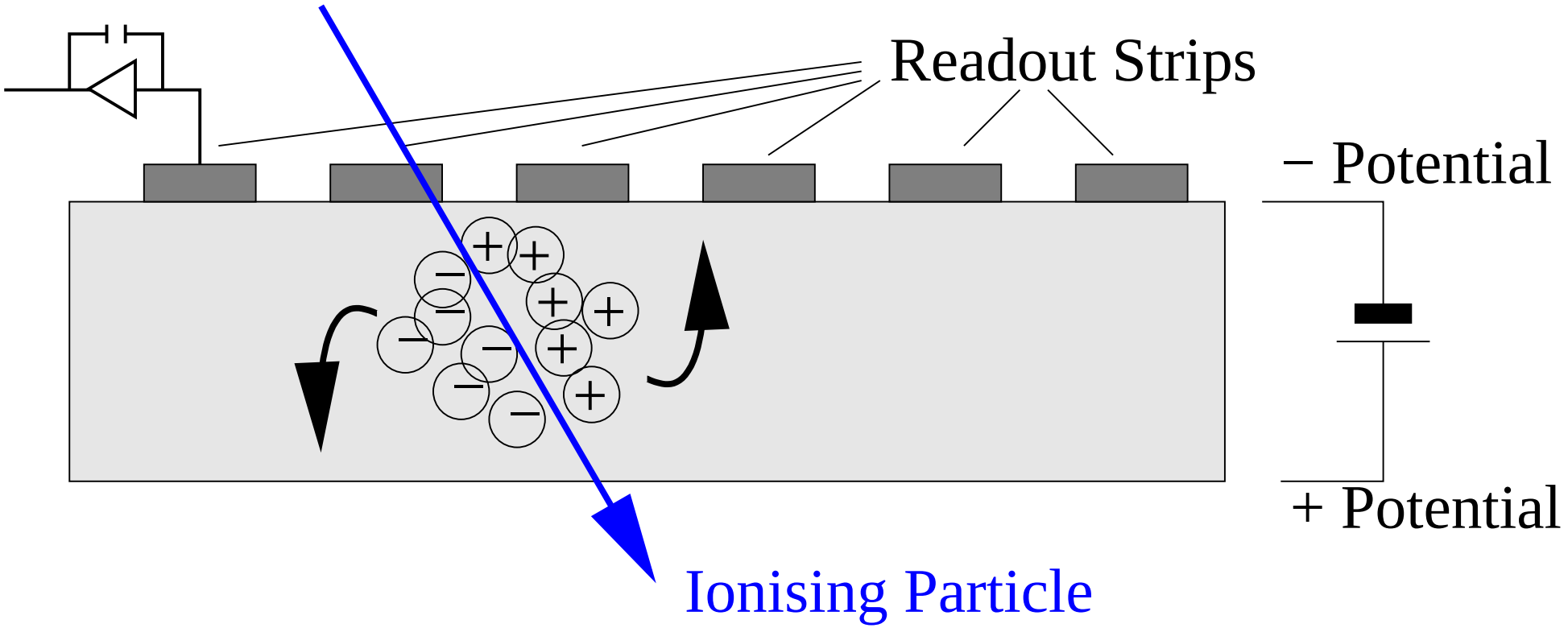


Silicon Detector

Principle of Operation



Principle of Operation



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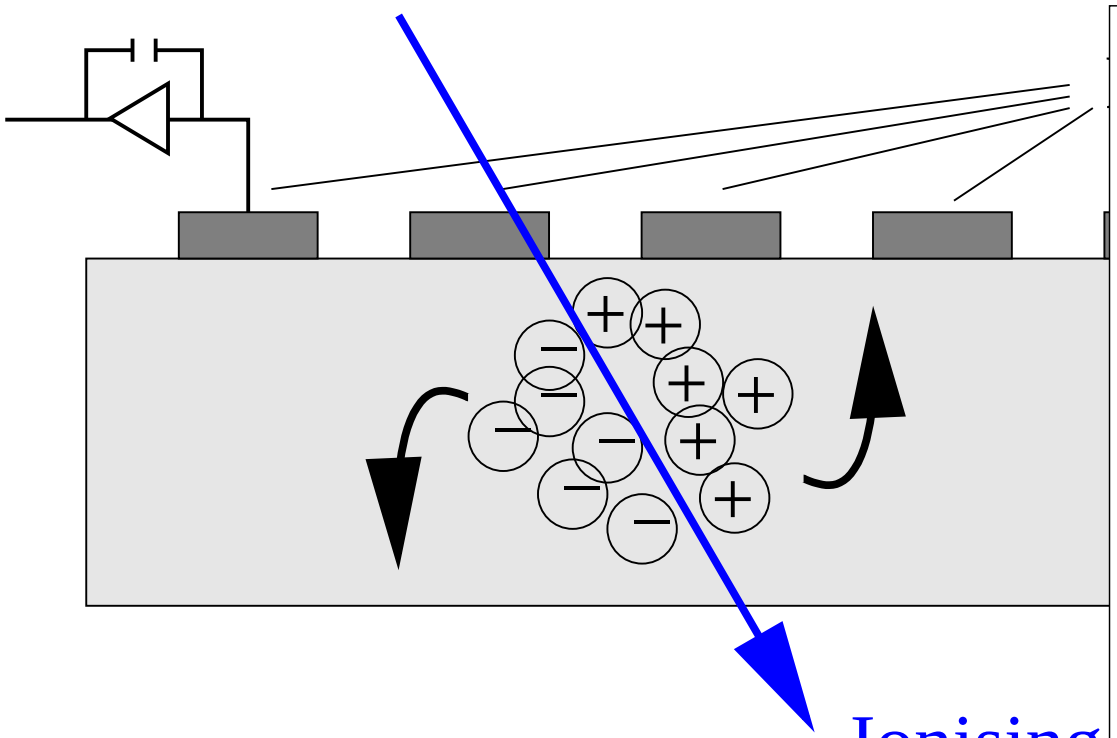
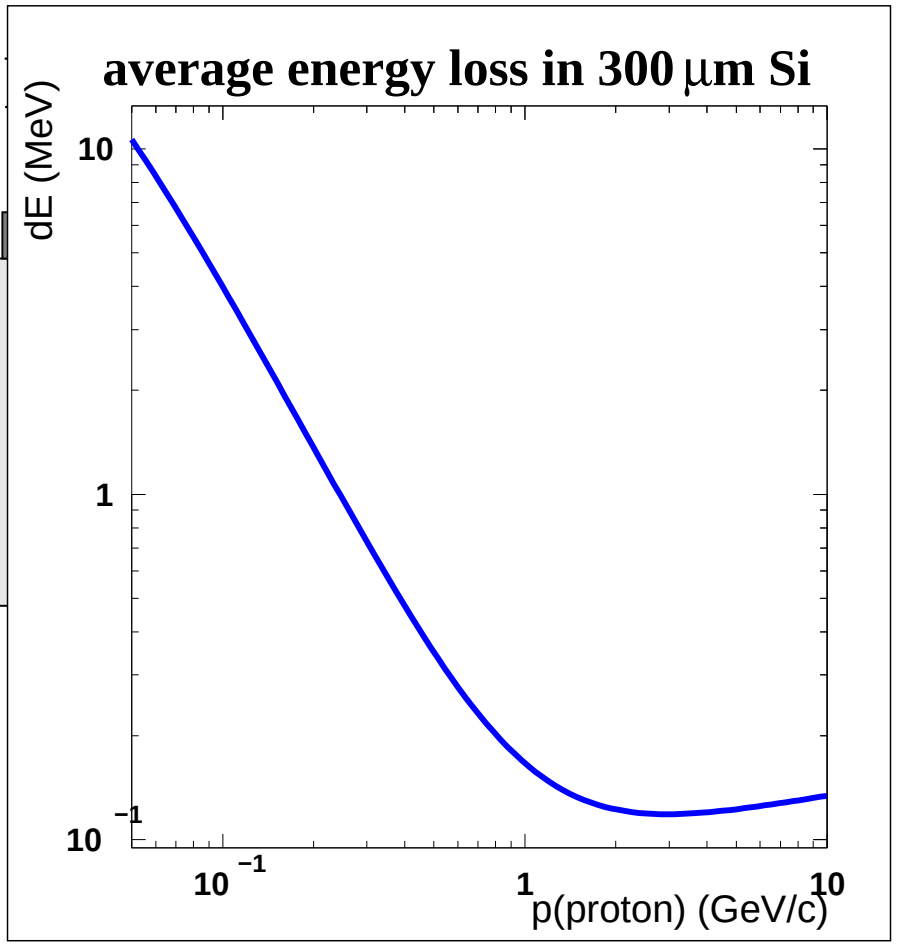
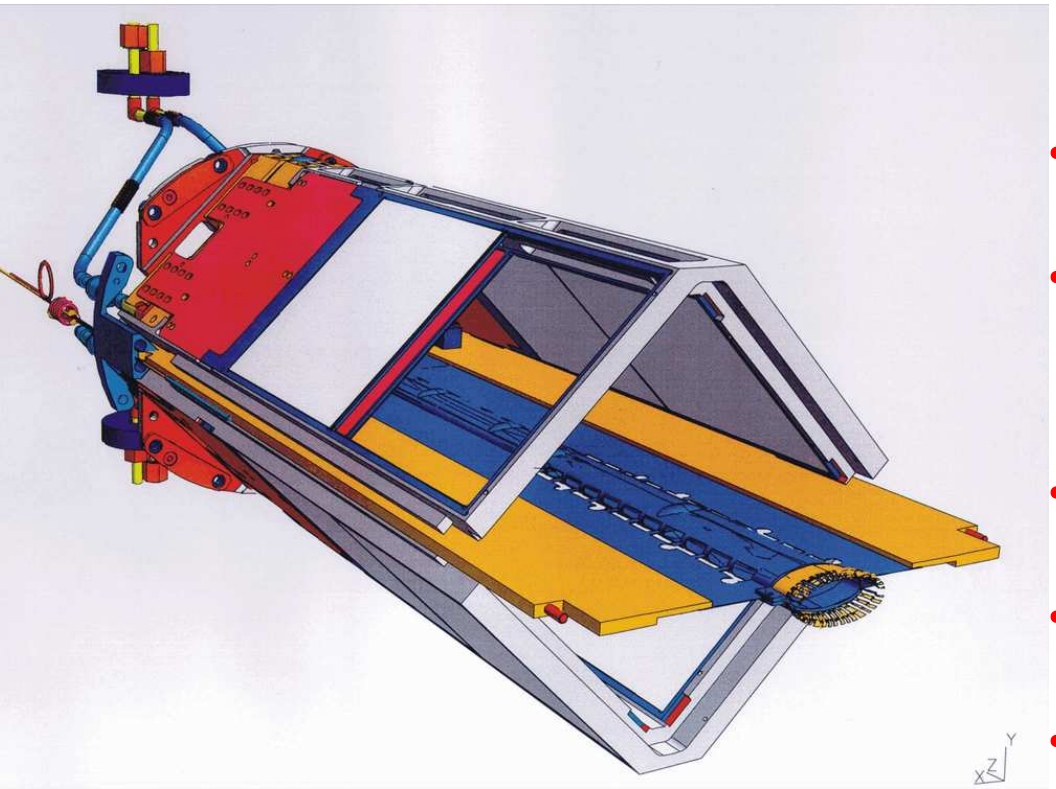


Ionising



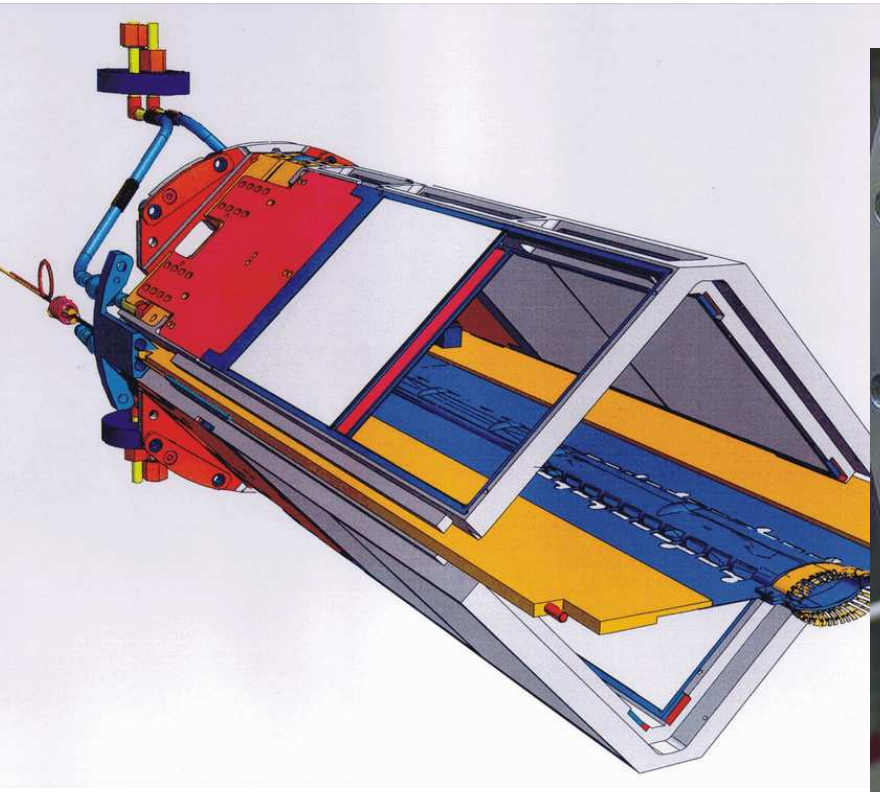
Recoil Silicon Detector

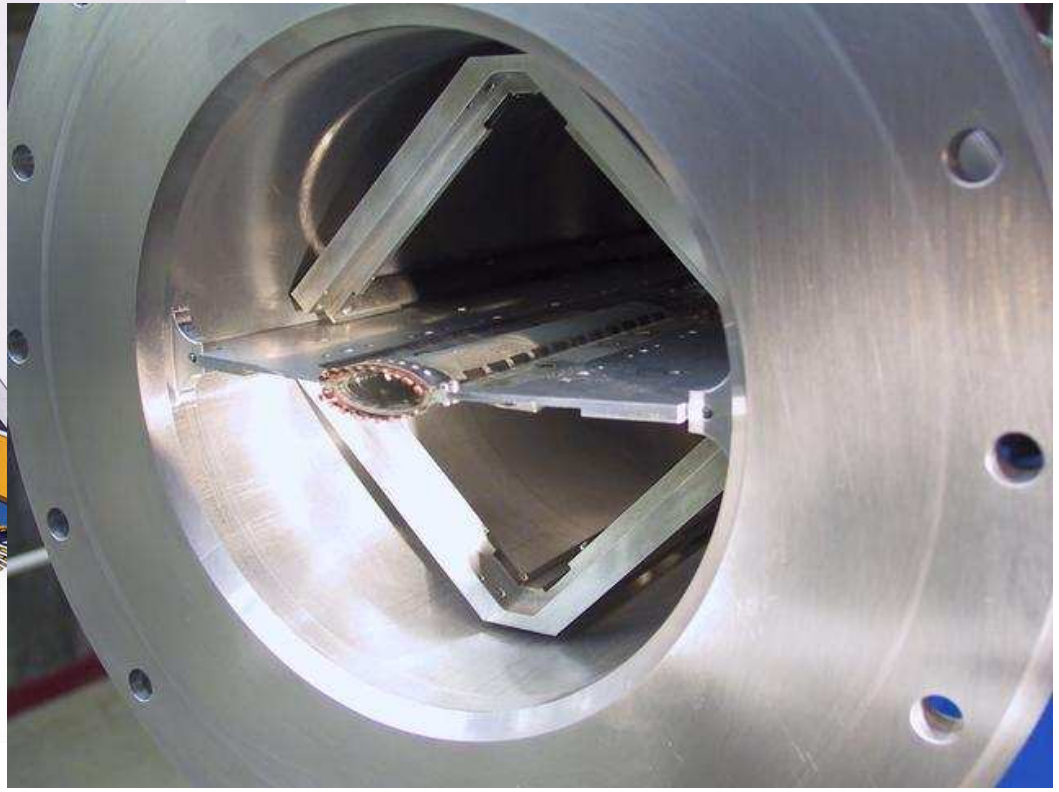


- Inside beam vacuum
- Diamond shape around target cell
- 2 layers of silicon
- 76 % of ϕ
- $23^o < \theta < 80^o$

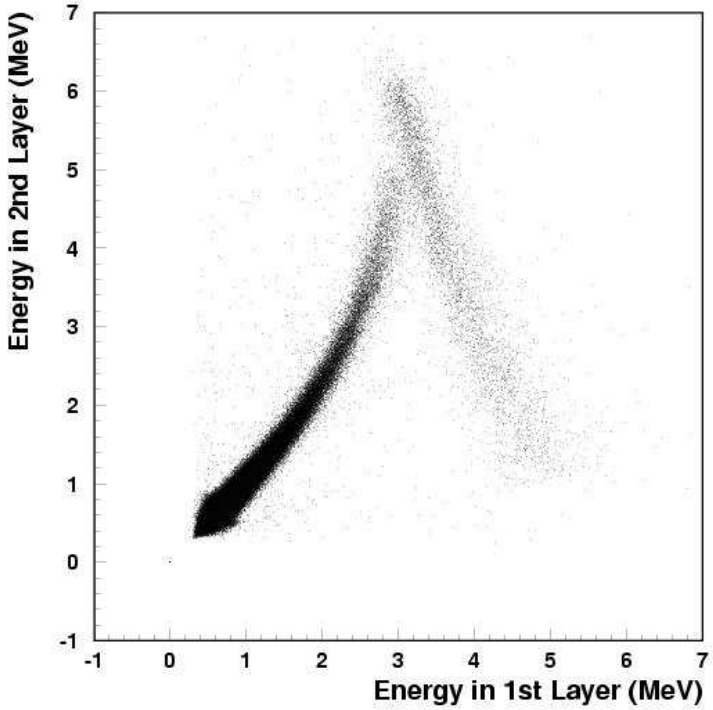
- Project of DESY,Erlangen,Gent,Glasgow

Recoil Silicon Detector





Recoil Silicon Detector



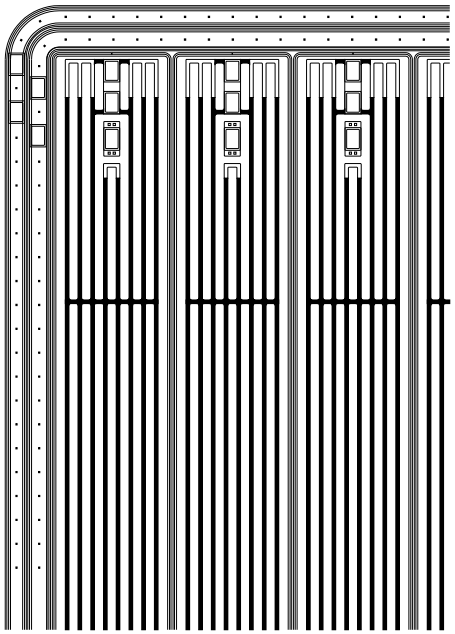
Recoil Silicon Detector

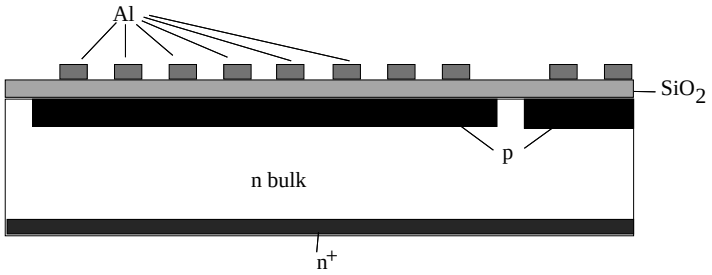
Most important Requirements:

- ➜ Large Dynamic Range required
- ➜ Vacuum compatible components
- ➜ Response linear with particle momentum

Silicon Sensors

TIGRE sensors





- Largest commercially available silicon sensor
- Double sided
- 99 $\times$ 99 mm^2, 300 μm thick
- 758 μm pitch
- Strip width: 702 μm
- SiO_2 layer ensures AC-coupling

TIGRE sensors

All TIGREs have been tested:

- Bias resistors p/n side for 3 strips
  - 3 strips: left, middle, right
- Interstrip resistance for 3 strips
- Coupling capacitor resistance for 3 strips
- Overall I/V–C/V characteristics: diode functionality, depletion voltage
- Long Term Test

The Holding Frame

A Holding Frame

Requirements for the holding frame:

- ➜ Sufficient stability
- ➜ Suitable for vacuum applications
- ➜ Thermal expansion coefficient close to that of silicon

A Holding Frame

	Silicon	Aluminium	Graphite	Shapal-M	Unit
Resistance	$10^{-4} - 10^{4}$	$5 \cdot 10^{-6}$	0.02	10^{12}	$\Omega \cdot cm$
Thermal Expansivity	2.6	23	7.4	4.4	$\frac{10^{-6}}{K}$
Modulus of Elasticity	170	70	15	160	GPa
Thermal Conductivity	150	130	65	100	$\frac{W}{m \cdot K}$
Outgassing Rate	n.a.	10^{-10}	$8 \cdot 10^{-11}$	$2.3 \cdot 10^{-11}$	$\frac{\text{mbar} \cdot l}{s \cdot \text{cm}^2}$
Costs per frame	n.a.	30	110	1200	€

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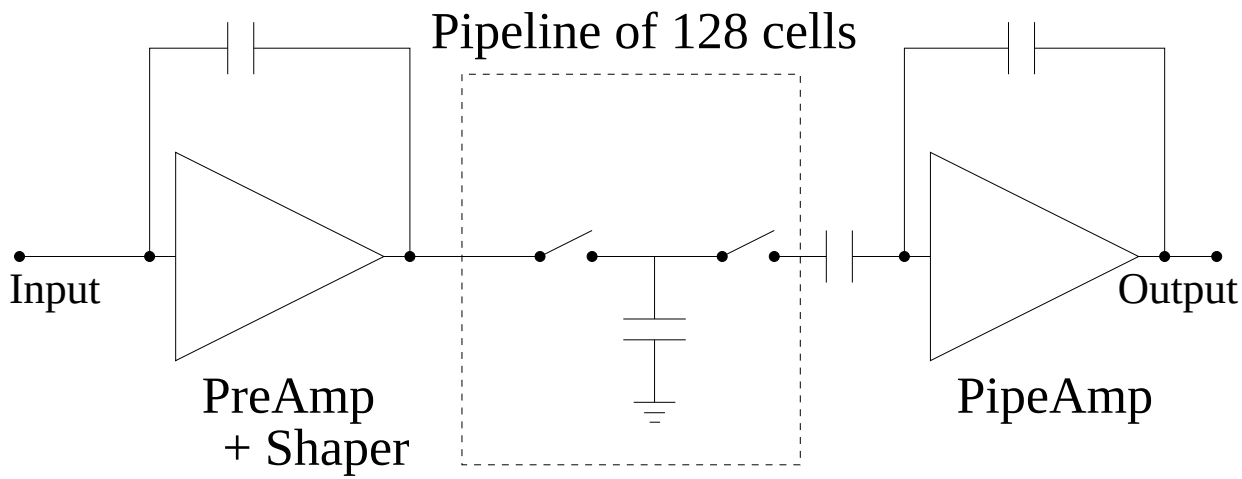
Go for Shapal-M

➠ Sensors are glued with two component epoxy glue at 150^{o}

Readout Hybrid

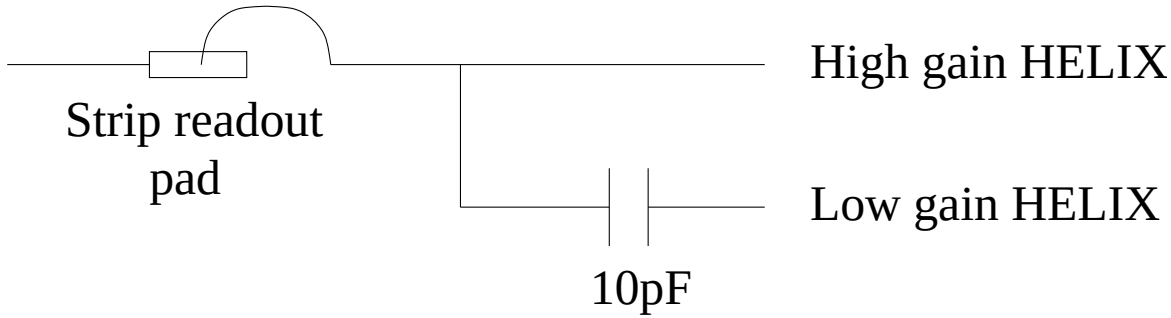
Readout Hybrid

Two readout chip candidates were tested: APC and HELIX128-3.0



Readout Hybrid

Extend Dynamic range with Charge division method:



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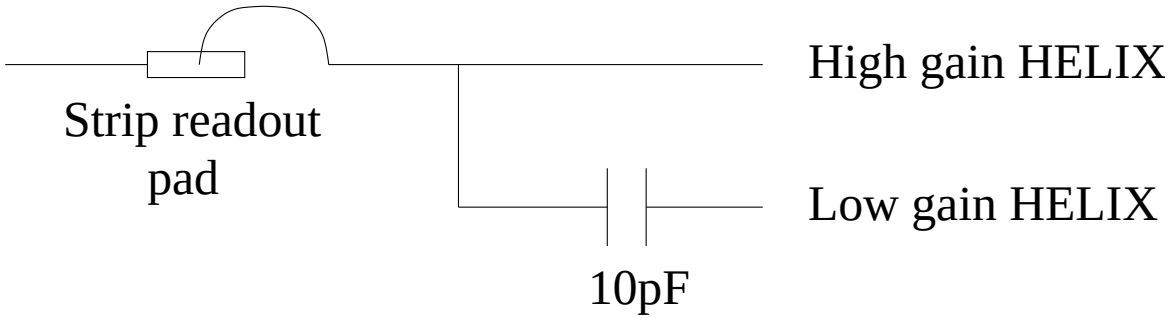
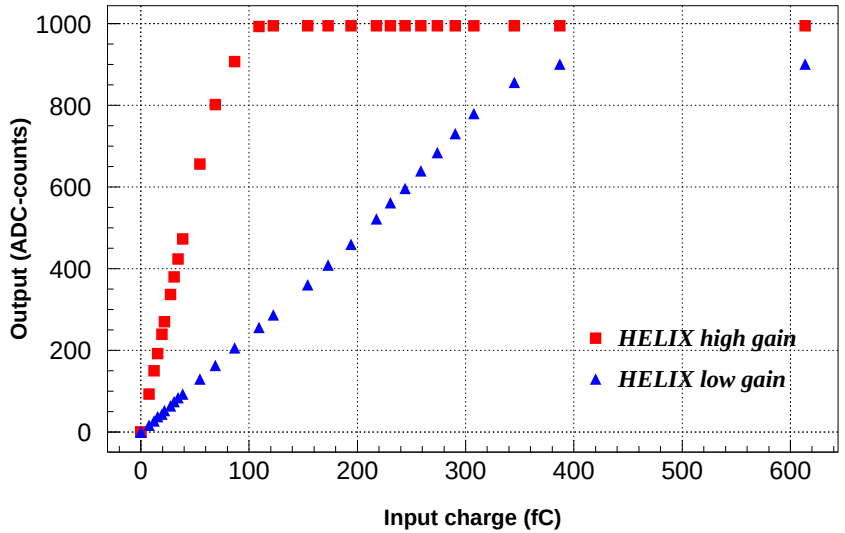
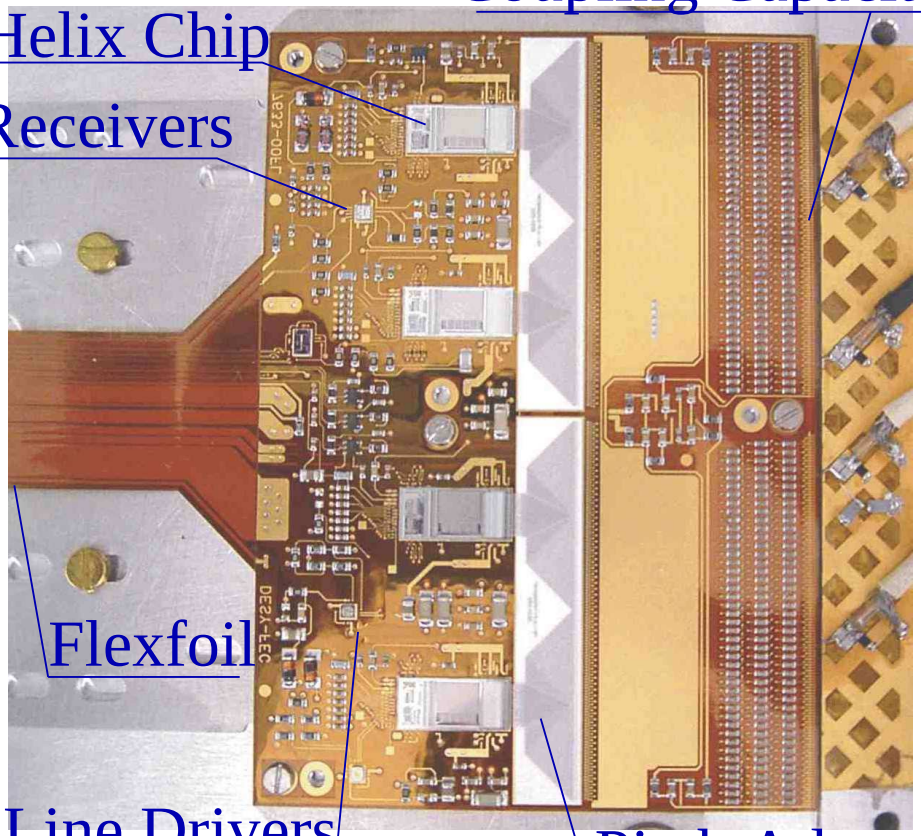


- Sufficient Dynamic Range
- HELIX already used in HERMES

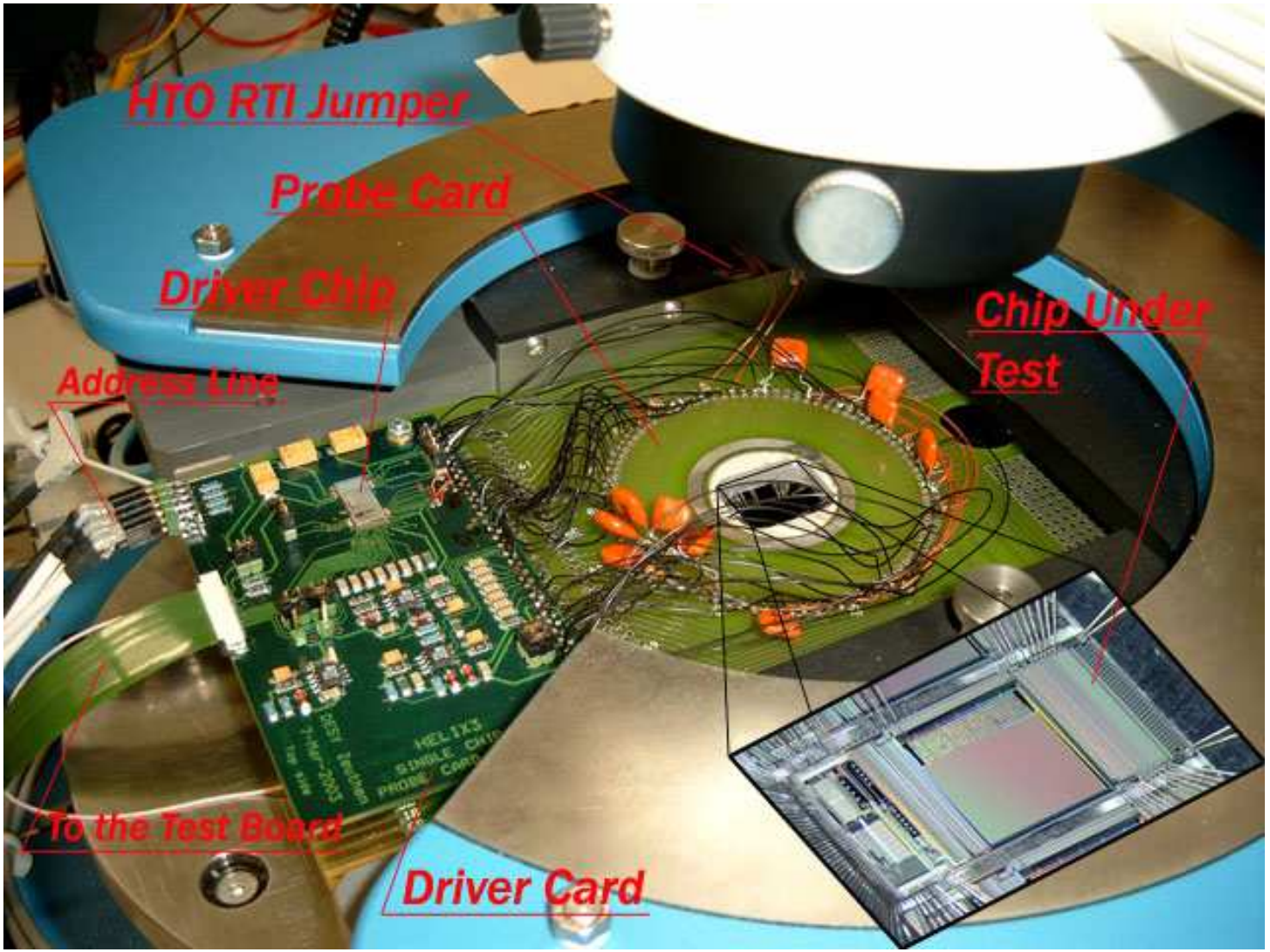


Readout Hybrid



- 4 layers, with kapton cores
- Glued to aluminum heatsink

Chip Tests

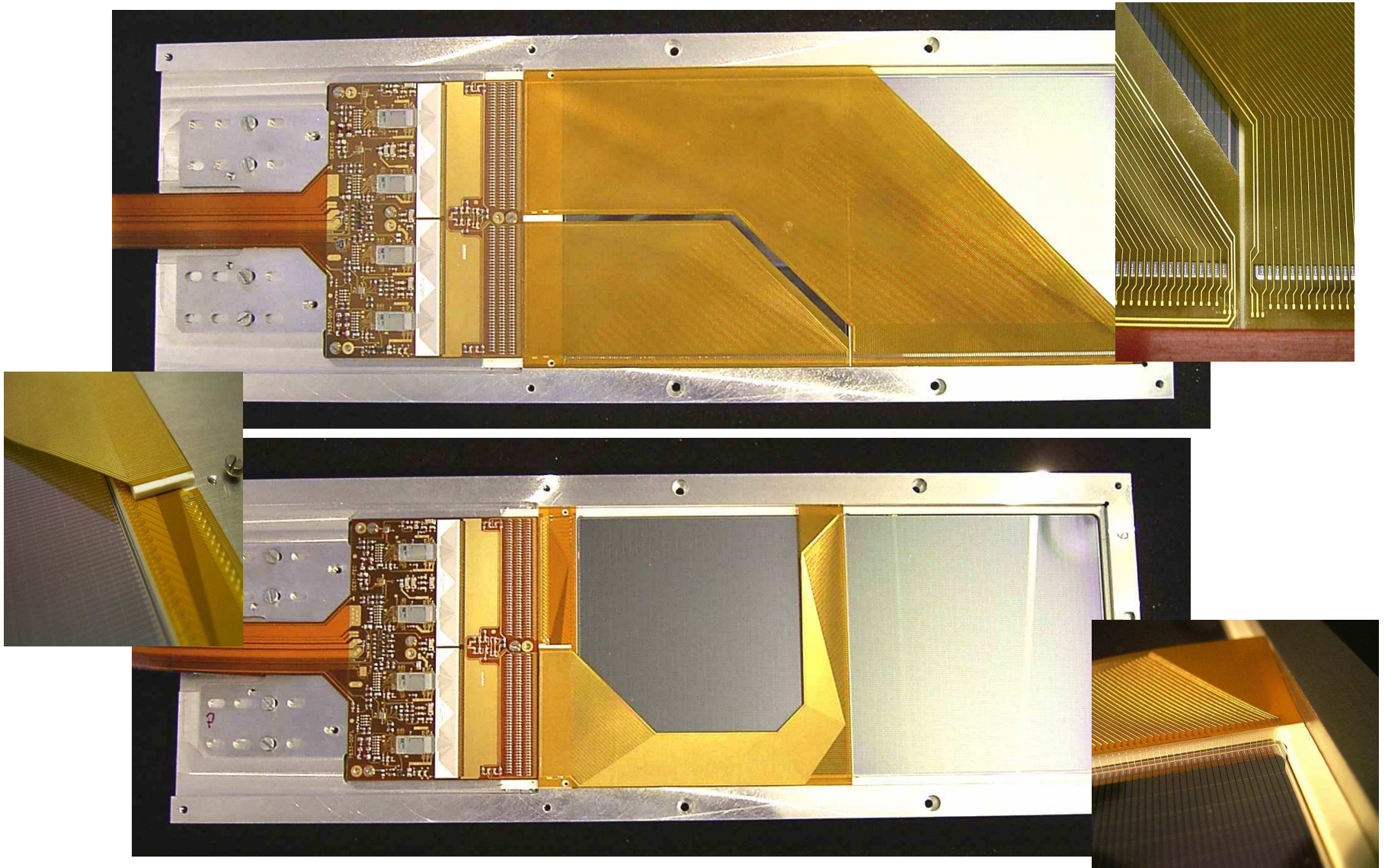

HTO RTI Jumper
Probe Card
Driver Chip
Address Line
Chip Under Test
To the Test Board
Driver Card

Chip Tests

- Basic functionality (addressing, programming)
- Uniformity checked with internal testpulse
- 372 chips tested
  - 64 chips needed
  - 153 Class A chips
  - 100 Class A1

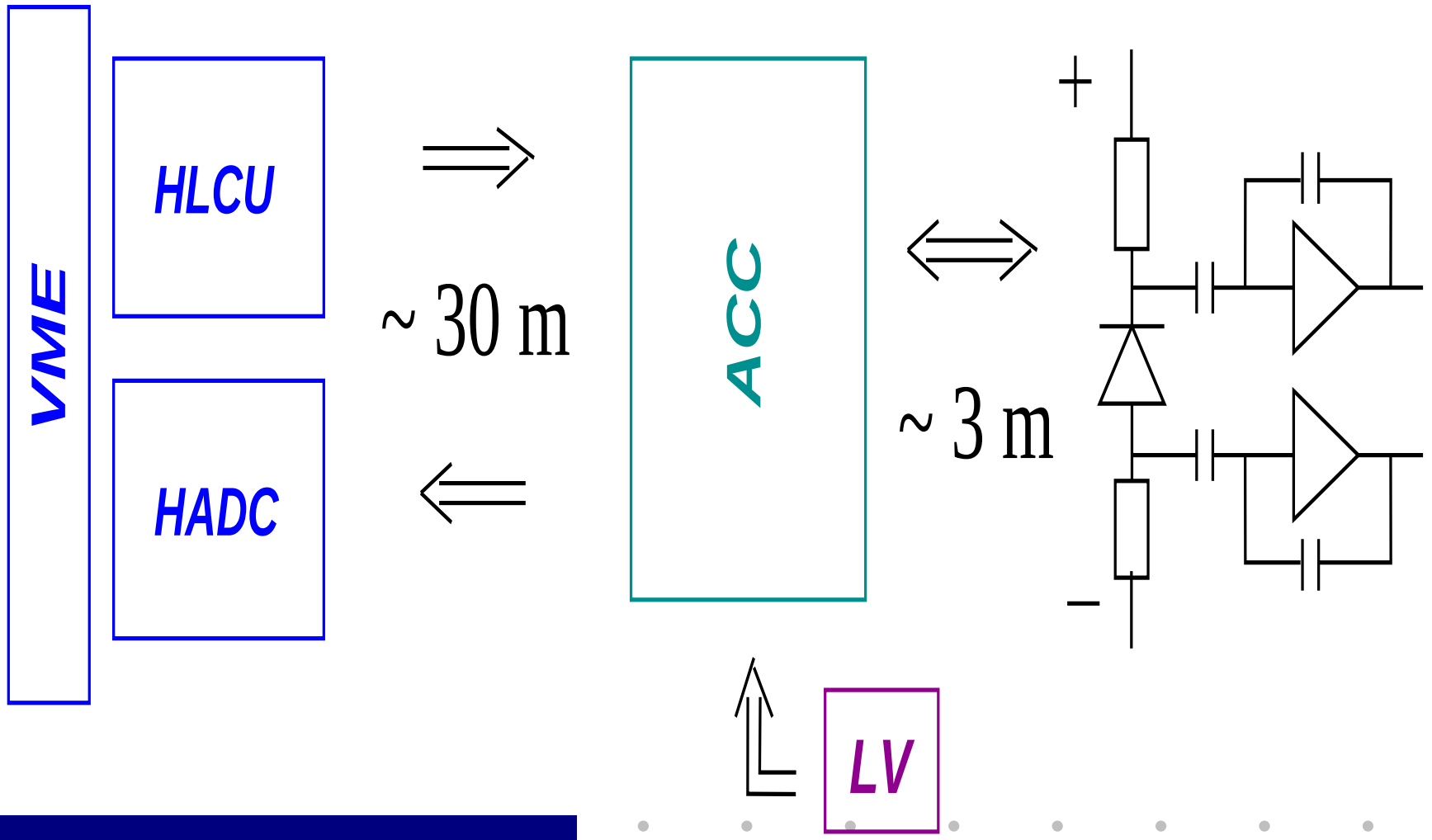
A Module

An SRD Module



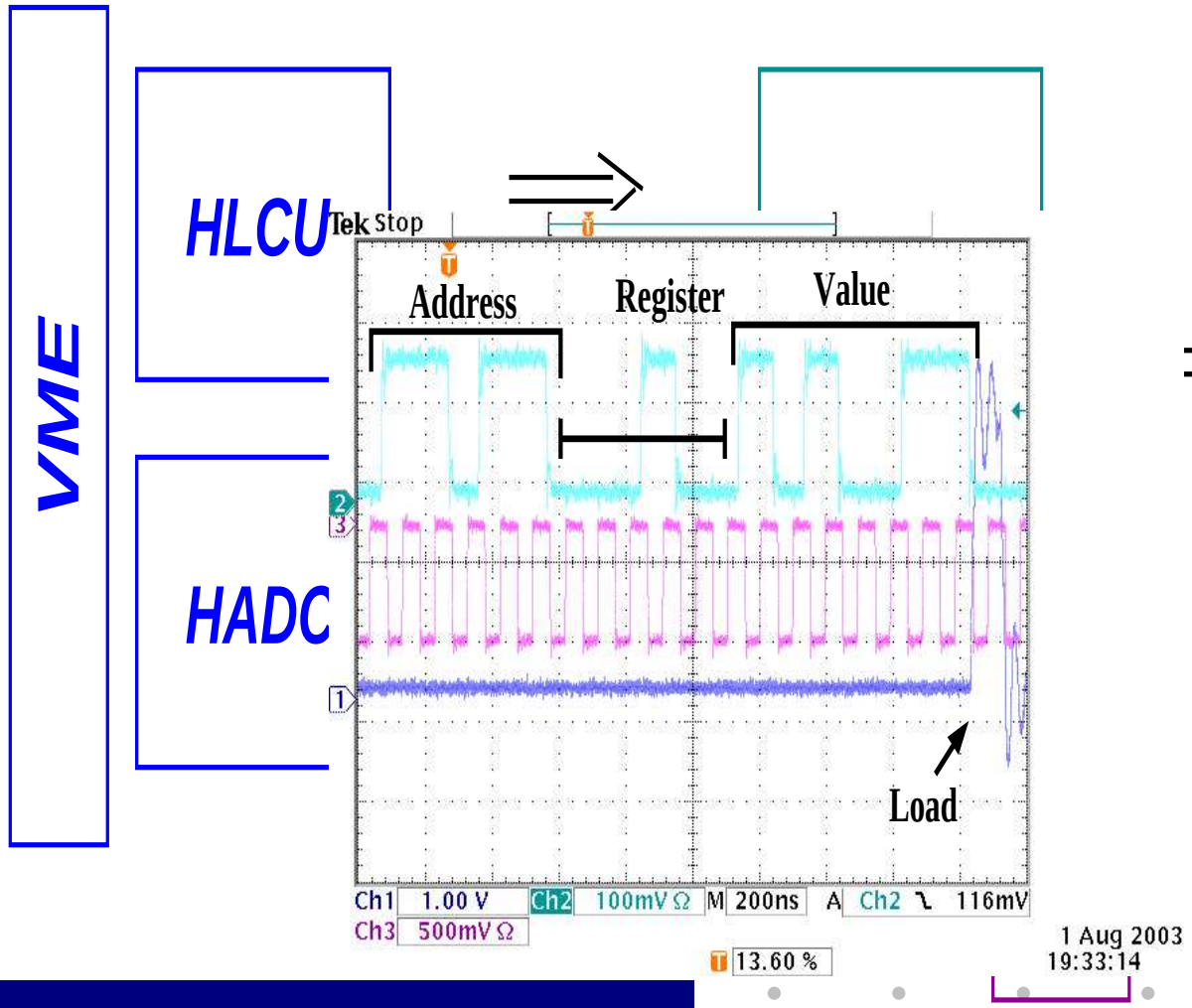
Readout Scheme

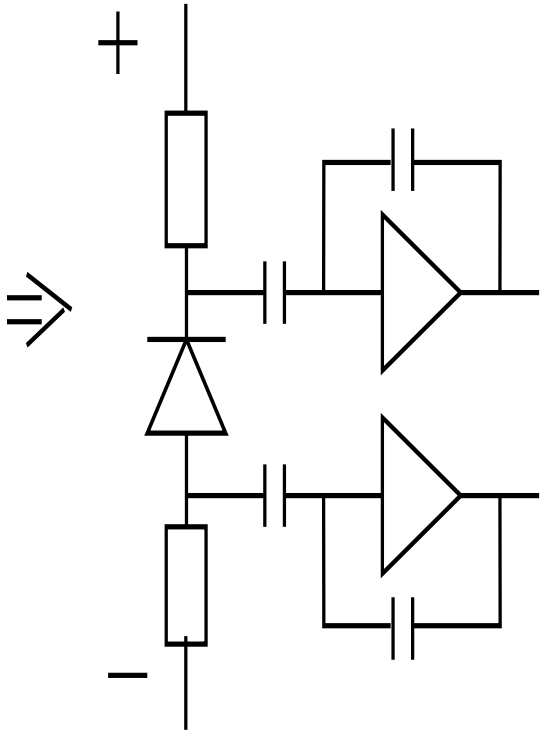
Readout Scheme



Readout Scheme

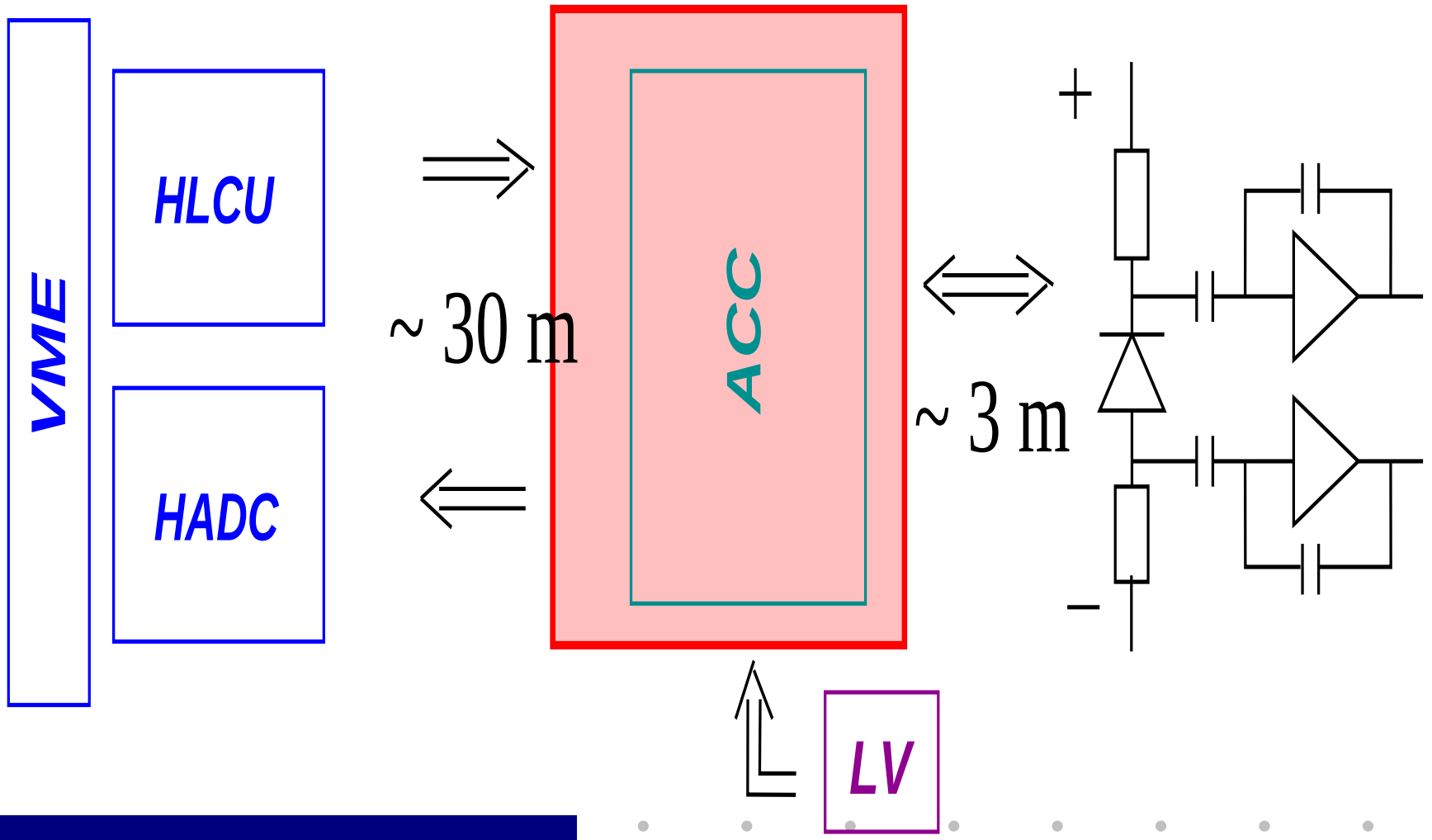
HLCU: Programming,Clock,Triggering



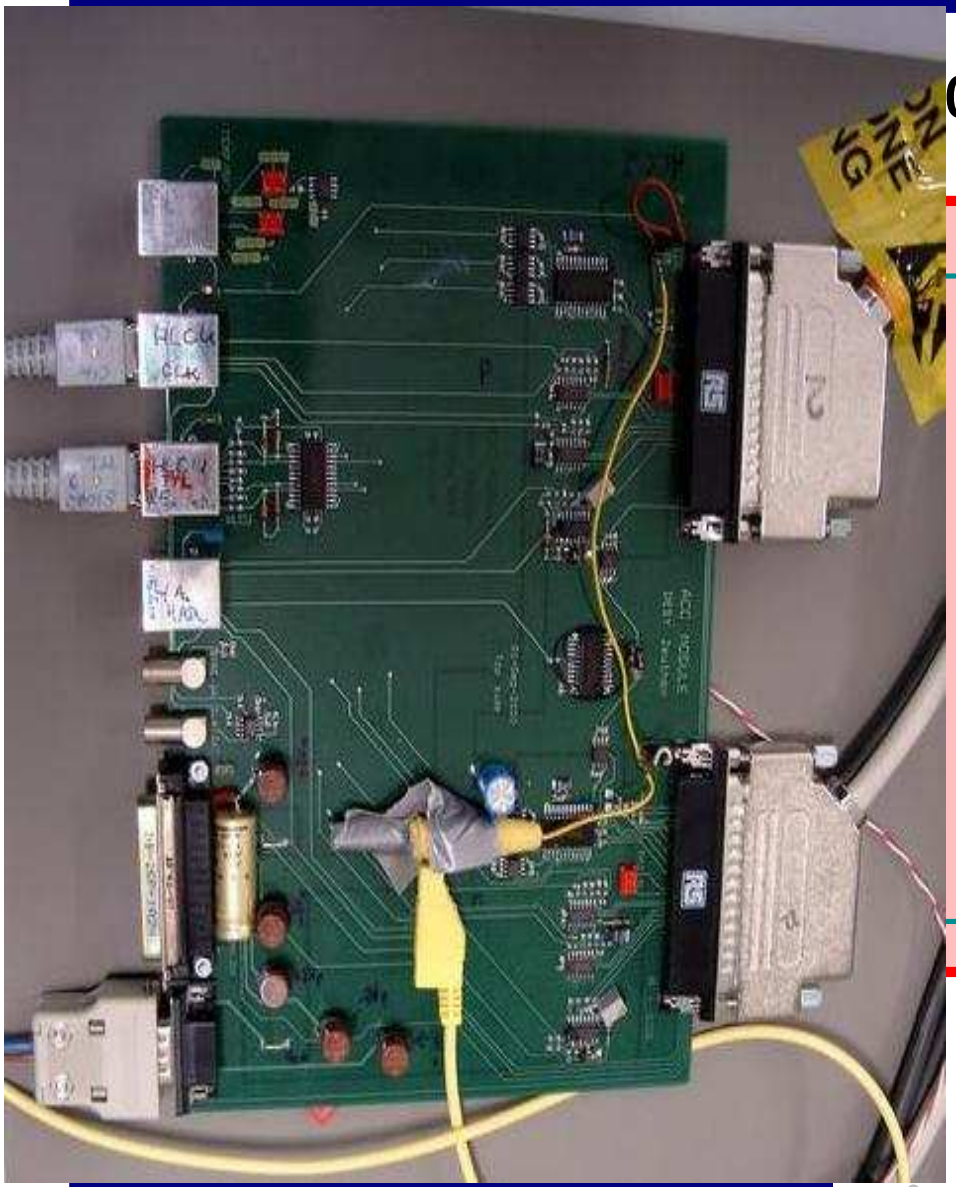


Readout Scheme

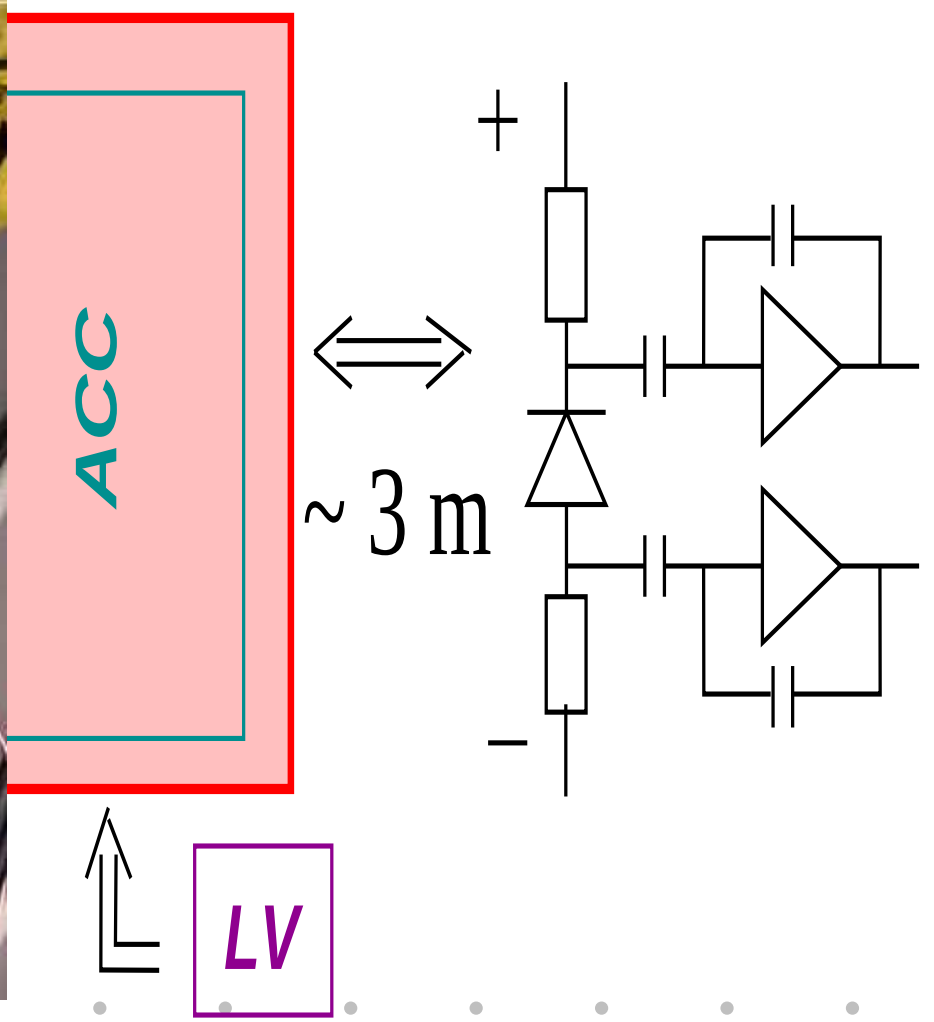
ACC: Repeater board, drivers/receivers



Readout Scheme

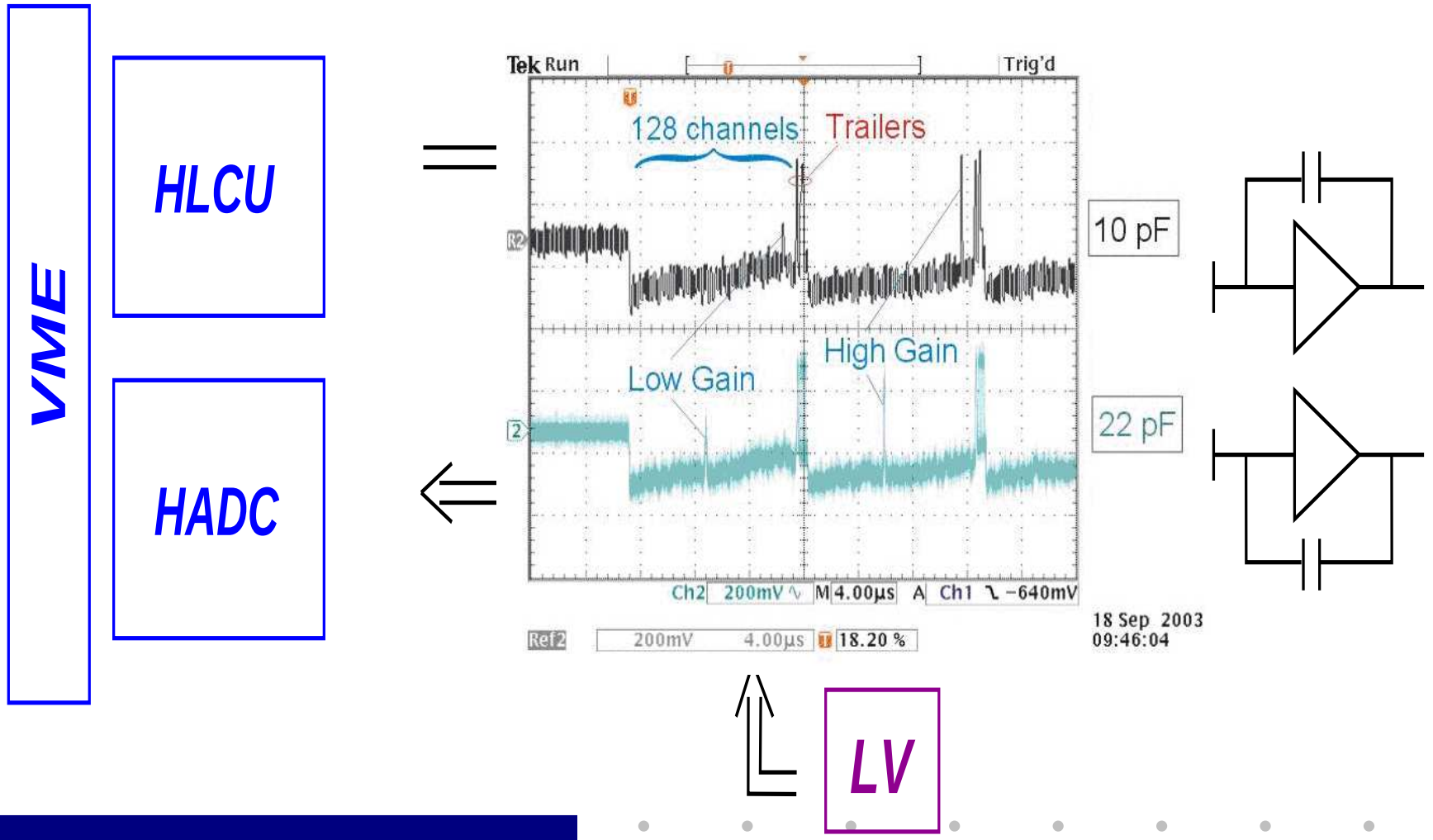


drivers/receivers



Readout Scheme

HADC: ADC, CMC, Zero Suppression



Testing

Prototype Testing

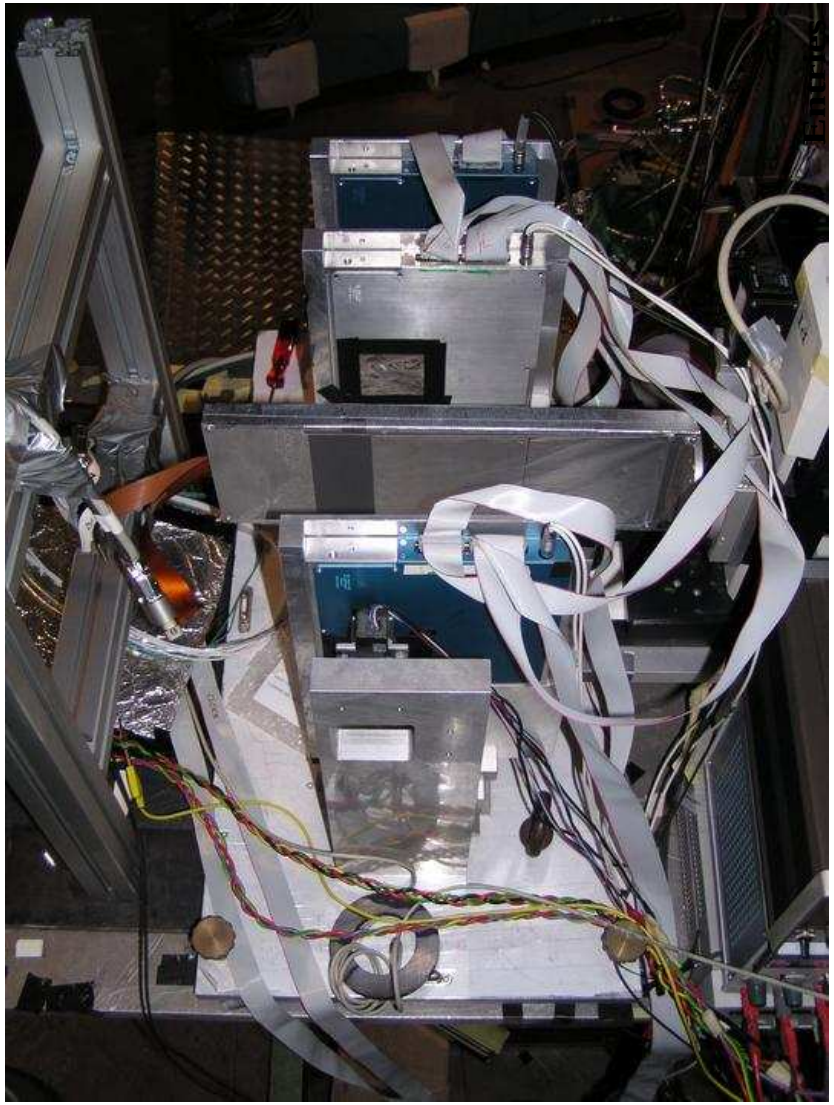
- Testbeams
  - DESY: MIP
  - Erlangen: Low Energy protons
- Laser Test Stand
- Detailed noise optimisation
- Parameter tests

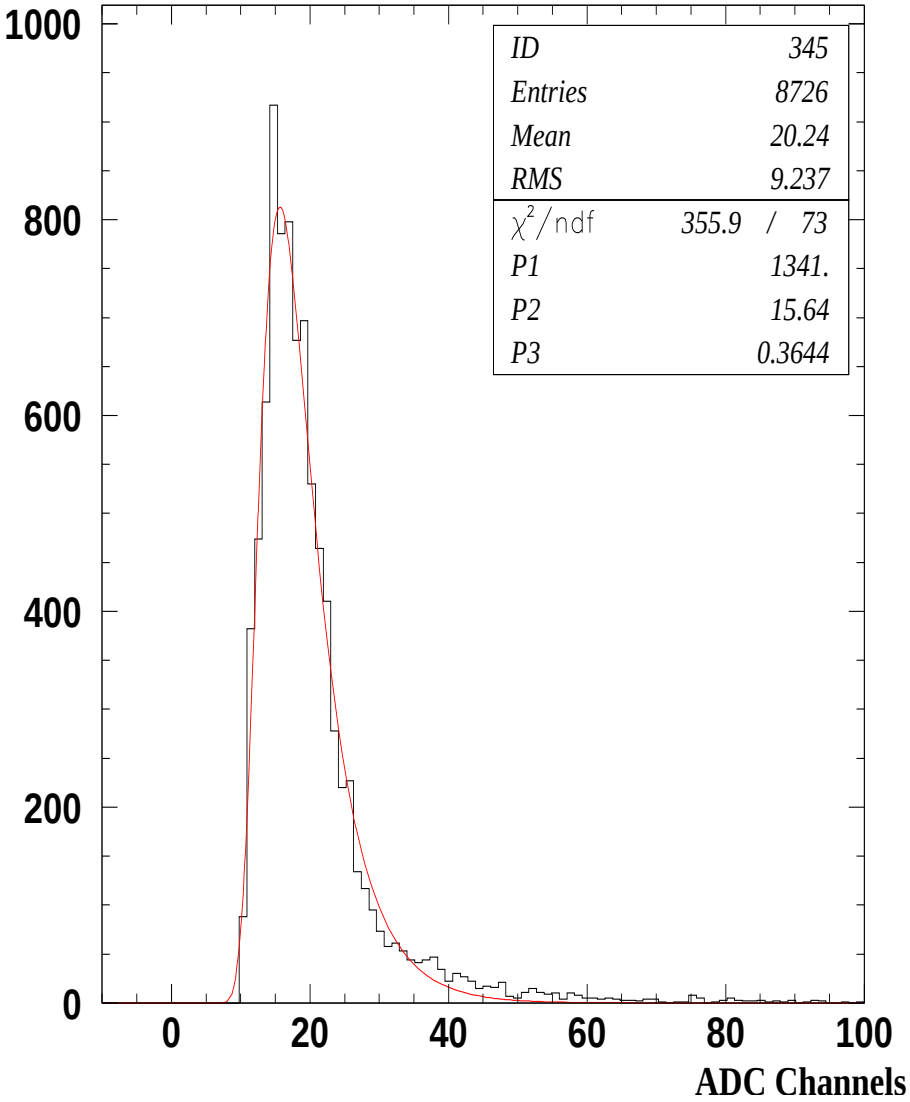
Zeuthen Lab

Zeuthen Lab

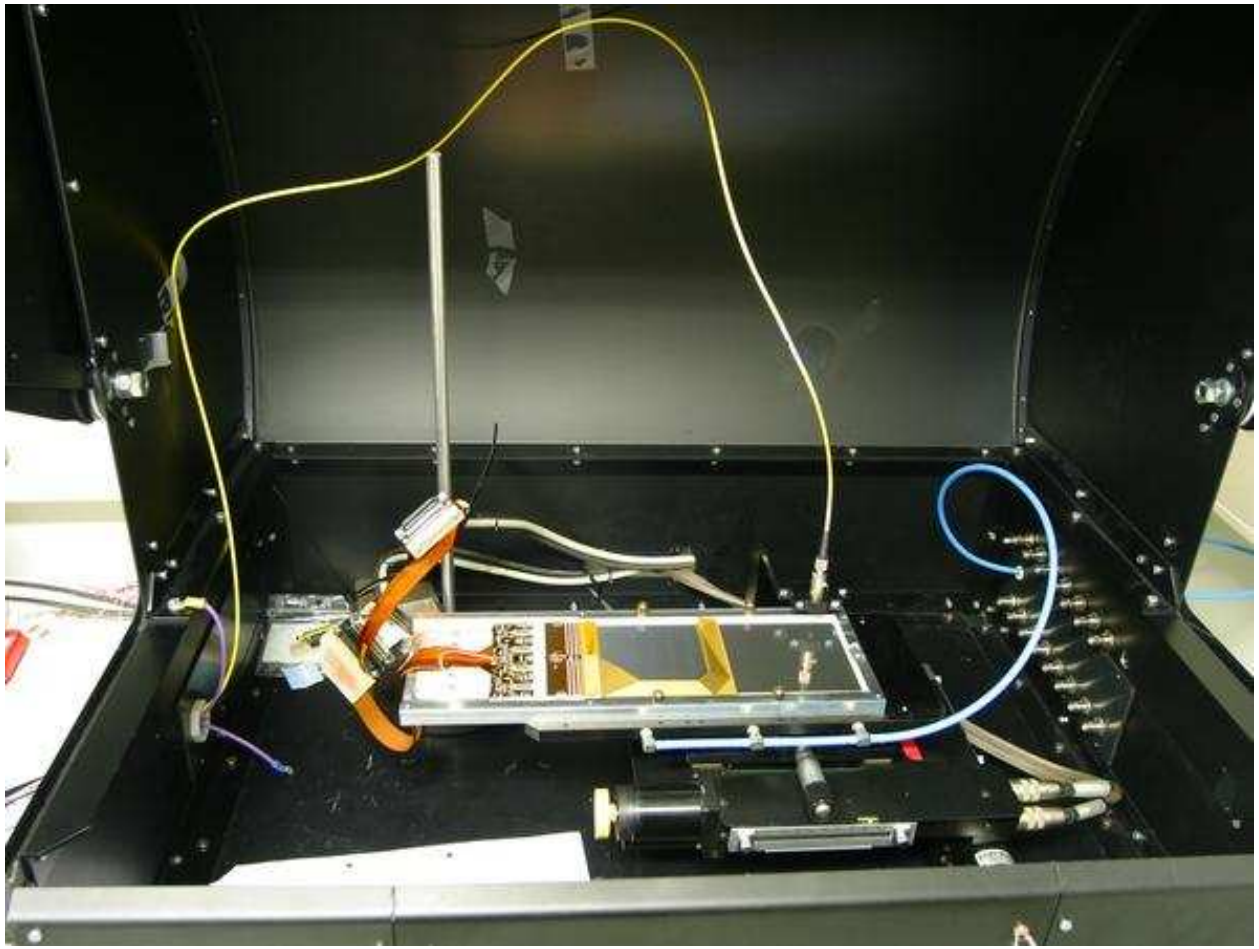



Testbeam at DESY



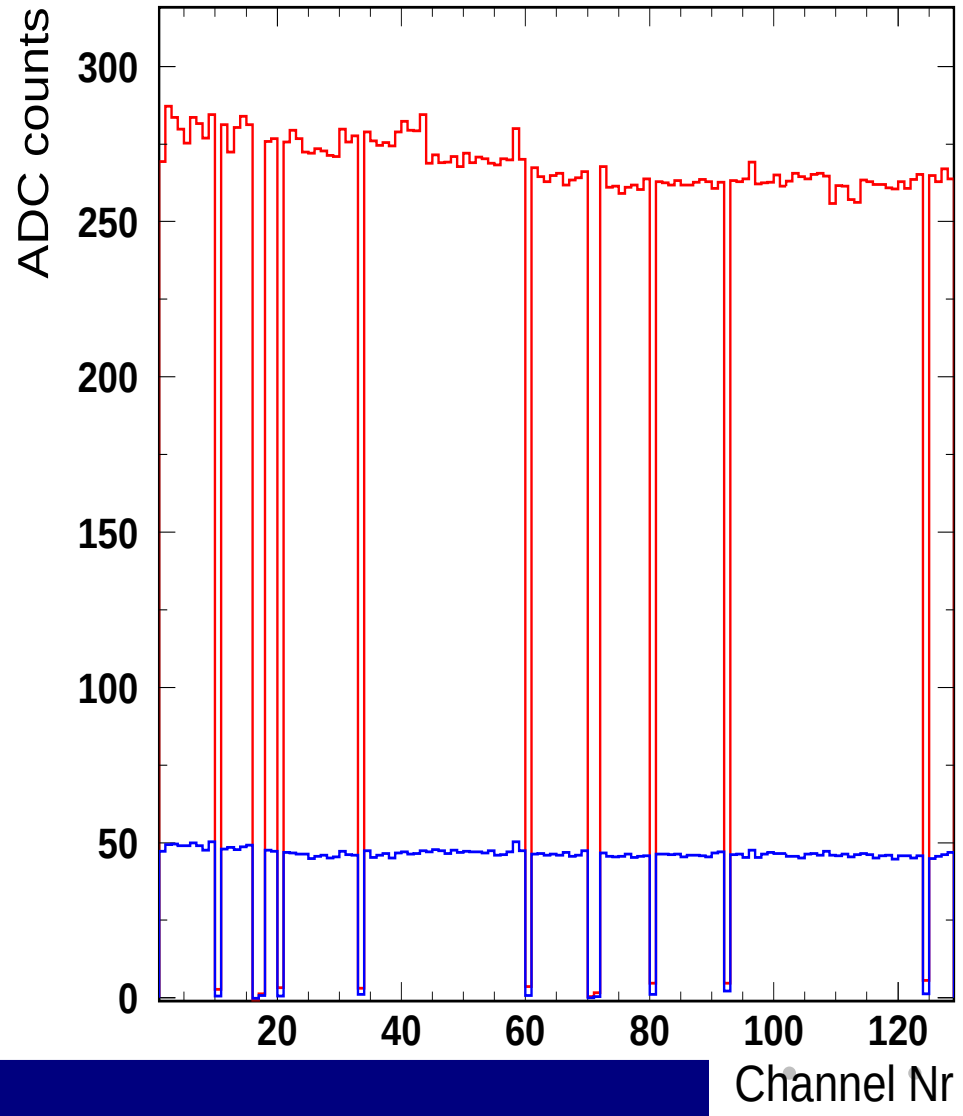


Laser Test



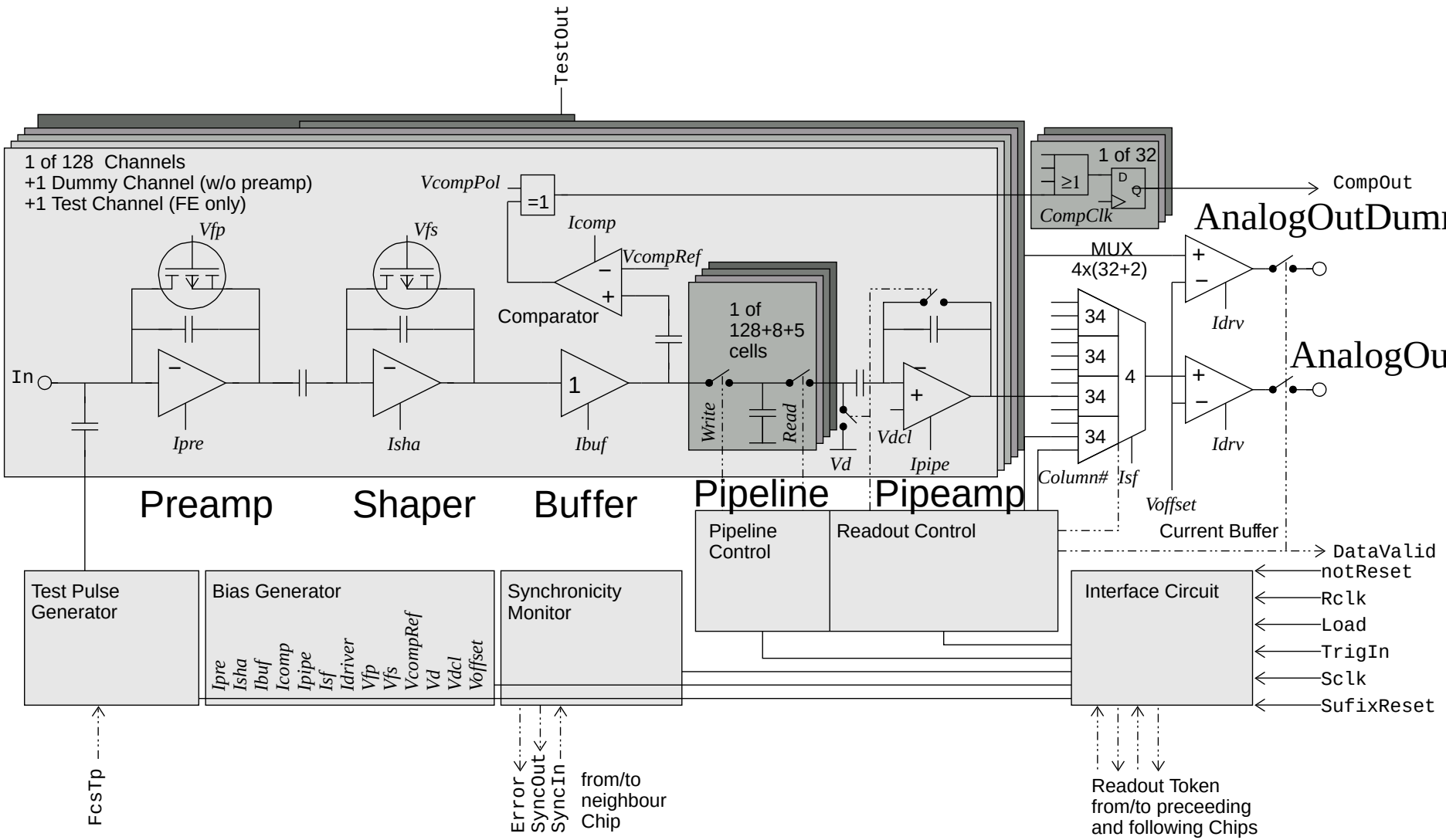
- Black Box
- Red Laser
- X-Y Table
- Spot $\sim 20\mu m$

Laser Test



- Uniformity
- Linearity
- Pipe Spread

Parameter Tests



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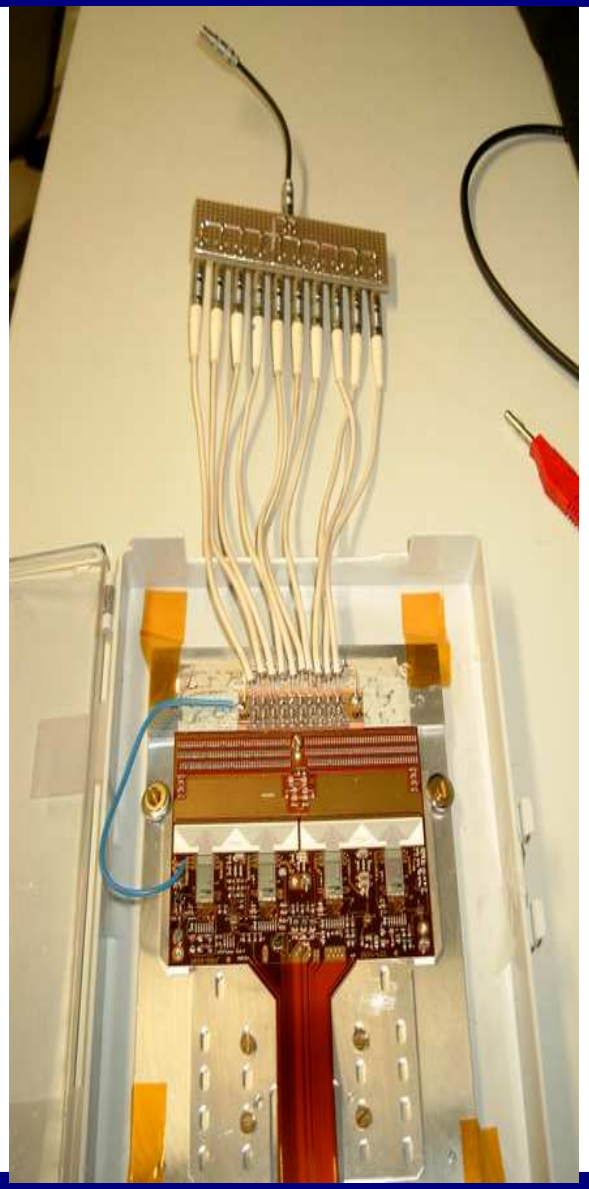

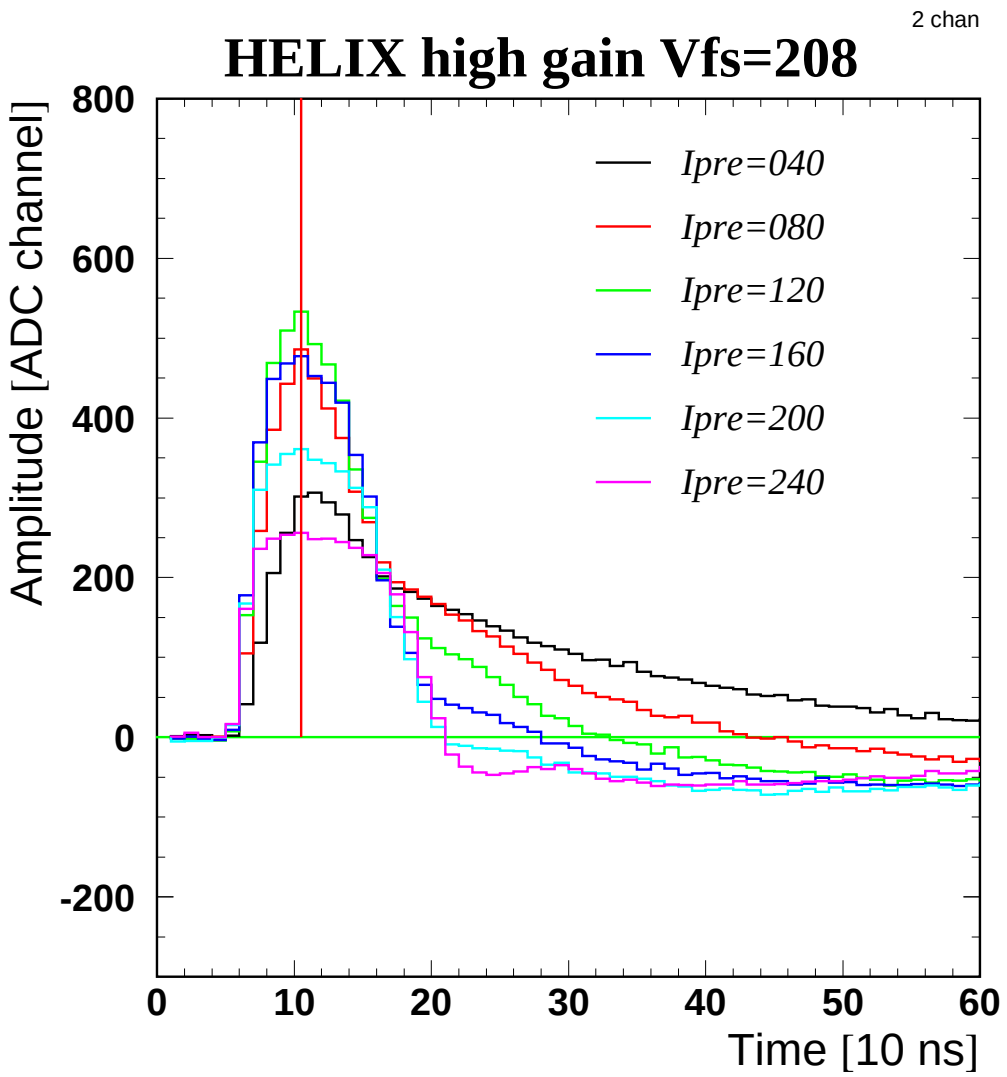

Summary

- Development of a Silicon Recoil Detector for HERMES
- Mechanical construction fixed and working
- First SRD module being tested and optimised
- Test installation in 2004

Danke Schön

- Mechanische Werkstatt
- Elektrische Werkstatt
- Rechenzentrum